

What is claimed is:

1. A method of forming a patterned thin film including a linear portion by frame plating, the method comprising:

5 the step of forming a frame having an undercut near a bottom thereof on a base layer; and

the plating step of forming the patterned thin film by plating through the use of the frame such that the linear portion has a portion close to the base layer, the portion having a width greater than a width of the remaining portion of the linear portion.

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2. The method according to claim 1, wherein the patterned thin film is formed to include a plurality of linear portions disposed side by side.

3. A patterned thin film disposed on a base layer and including a linear
15 portion, wherein the linear portion has a portion close to the base layer, the portion having a width greater than a width of the remaining portion of the linear portion.

4. The patterned thin film according to claim 3, including a plurality of
20 linear portions disposed side by side.